

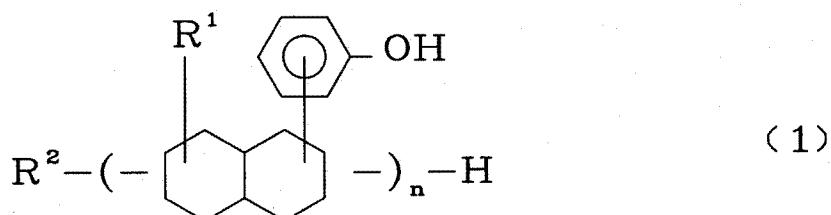
**AMENDMENTS TO THE CLAIMS, COMPLETE LISTING OF CLAIMS  
IN ASCENDING ORDER WITH STATUS INDICATOR**

Please amend the following claims as indicated.

1. (Currently Amended) A thermosetting resin composition characterized as containing an epoxy resin having an epoxy equivalent weight of 100 - 2,000, an epoxy hardener in the form of a compound having a phenol group, and a layered silicate in the amount of 0.2 - 100 parts by weight, based on 100 parts by weight of resin constituents including said epoxy resin and epoxy hardener, and

wherein said epoxy hardener comprises at least one type selected from the group consisting of hydrophobic phenol compounds represented by the following formulas (1) - (3):

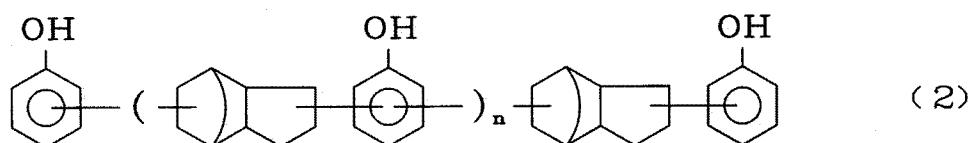
[Chemical 1]




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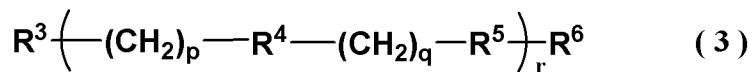
(In the formula (1),  $R^1$  denotes methyl or ethyl,  $R^2$  denotes hydrogen or a hydrocarbon group and  $n$  indicates an integer of 2 - 4)

[Chemical 2]



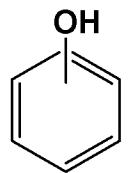
(In the formula (2), n indicates 0 or an integer of 1 – 5) and

[Chemical 3]

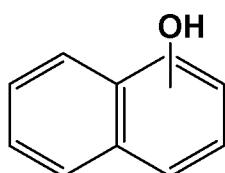


(In the formula (3), R<sup>3</sup> denotes a group represented by the following formula (4a) or (4b), R<sup>4</sup> denotes a group represented by the following formula (5a), (5b) or (5c), R<sup>5</sup> denotes a group represented by the following formula (6a) or (6b), R<sup>6</sup> denotes hydrogen or a molecular chain group containing 1 – 20 carbon atoms, p and q independently indicate an integer of 1 – 6, and r indicates an integer of 1 – 11).

[Chemical 4]

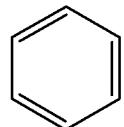


( 4a )

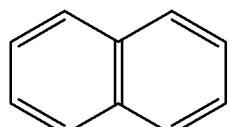


( 4b )

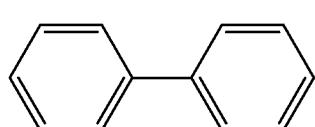
[Chemical 5]



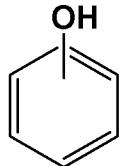
( 5a )



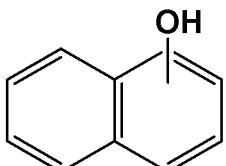
( 5b )



( 5c )

[Chemical 6]

( 6a )



( 6b )

2. (Original) The thermosetting resin composition as recited in claim 1, characterized in that said epoxy resin contains at least one type selected from the group consisting of a bisphenol epoxy resin, biphenyl epoxy resin, dicyclopentadiene epoxy resin and naphthalene epoxy resin.

3. (Canceled).

4. (Previously Presented) The thermosetting resin composition as recited in claim 1, characterized in that said layered silicate comprises at least one type selected from the group consisting of montmorillonite, hectorite, swelling mica and vermiculite.

5. (Previously Presented) The thermosetting resin composition as recited in claim 1, characterized in that said layered silicate contains at least one type of ammonium salt selected from the group consisting of alkyl ammonium salt containing 6 or more carbon atoms, aromatic quaternary ammonium salt and heterocyclic quaternary ammonium salt.

6. (Currently Amended) A resin sheet characterized as comprising the thermosetting resin composition as recited in any one of claims 1, 2, 4 and– 5.

7. (Original) A resin sheet characterized in that it is obtained by curing the resin sheet as recited in claim 6.

8. (Previously Presented) The resin sheet as recited in claim 6, characterized in that a part or all of said layered silicate is dispersed in the form of a stack consisting of 5 or less layers and has a mean interlayer spacing of at least 3 nm along the (001) plane when measured by a wide-angle X-ray diffraction method.

9. (Previously Presented) The resin sheet as recited in claim 6, characterized in that it exhibits a mean linear expansion coefficient ( $\alpha_1$ ) of not exceeding  $4.0 \times 10^{-5} /^{\circ}\text{C}$  over a temperature range that is 10 – 50 °C lower than a glass transition temperature of a cured product of said thermosetting resin composition.

10. (Previously Presented) The resin sheet as recited in claim 6, characterized in that it exhibits a mean linear expansion coefficient ( $\alpha_2$ ) of not exceeding  $4.0 \times 10^{-5} /^{\circ}\text{C}$  over a temperature range that is 10 – 50 °C higher than a glass transition temperature of a cured product of said thermosetting resin composition.

11. (Previously Presented) The resin sheet as recited in claim 6, characterized in that a cured product of said thermosetting resin composition exhibits a dielectric constant at 1 GHz of not exceeding 3.3 and a dielectric loss tangent at 1 GHz of not exceeding 0.015.

12. (Previously Presented) A resin sheet for insulating substrate, characterized as comprising the resin sheet as recited in claim 6.